

FEATURES:

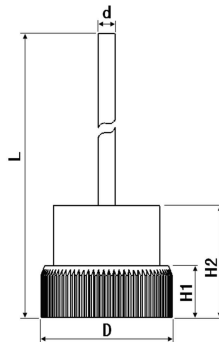
- Adopt a vacuum solder techniques with one-step soldering Technology. High Soldering Lug welds temperature, Good Consistency of Max. Forward Voltage Drop and Low ΔV_F Dispersion coefficient.
- Epoxy molded packages. Good hermetic closure, and strong resistance against bending, tension, humidity.
- O/J CHIP. Good consistency of Forward and Reverse feature, effective utilization of silicon area, small high temperature leaking Currency and good capacity of reverse surge current.
- Apply to each field Automotive Rectifiers Extensively.
- Replacement of LUCAS Type diodes.

Drawing and Dimension

CB35MN
N: CATHODE ON LEAD WIRE



CB35MP
P: ANODE ON LEAD WIRE



sym	Size (mm)
L	30±0.5
D	10.1+/-0.02
d	Φ1.30
H1	3.7
H2	8.0

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYM	UNIT	TYPE
			YZPST-CB35MP/N
Max. Average Forward current ($T_c = 170^\circ\text{C}$)	IF (AV)	A	35
Max. Peak, One-cycle forward, non-repetitive surge current	IFSM	A	400
Max. Forward Voltage Drop ($I_F=100\text{A}$, $T_c=25^\circ\text{C}$)	VFM	V	1.1
Max. Repetitive Reverse Peak Voltage	VRRM	V	25~29
Maximum reverse leakage current ($V_R=VRRM$, $T_C=25^\circ\text{C}$)	IRRM1	μA	1
Maximum reverse leakage current ($V_R=VRRM$, $T_C=175^\circ\text{C}$)	IRRM2	μA	800
ΔV_F Disperse Coefficient	(max-average)/average		≤15%
Max. Thermal Resistance, Junction to case	R_{thjc}	$^\circ\text{C}/\text{W}$	≤0.8
Storage temperature Range	T_{stg}	$^\circ\text{C}$	-40~200
Junction Temperature	T_{jm}	$^\circ\text{C}$	200

Note: DEVICE CODE: P= ANODE ON LEAD WIRE, N= CATHODE ON LEAD WIRE

Ni--Plated Ni; NS---Plated Ni and Sn

Ni: Copper Nickel 2~8 mincron NS: Tin plating 2~8 mincron after Nickel